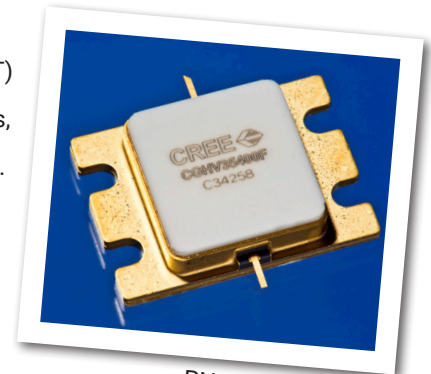


# CGHV35400F

400 W, 2900 - 3500 MHz, 50-Ohm Input/Output Matched, GaN HEMT for S-Band Radar Systems

Cree's CGHV35400F is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically with high efficiency, high gain and wide bandwidth capabilities, which makes the CGHV35400F ideal for 2.9 - 3.5 GHz S-Band radar amplifier applications. The transistor is supplied in a ceramic/metal flange package, type 440210.



PN: CGHV35400F  
Package Type: 440215

## Typical Performance Over 2.9-3.5 GHz ( $T_c = 85^\circ\text{C}$ ) of Demonstration Amplifier

Parameter	2.9 GHz	3.2 GHz	3.5 GHz	Units
Output Power	375	400	360	W
Gain	9.8	10	9.6	dB
Drain Efficiency	66	59	57	%

Note:

Measured in the CGHV35400F-AMP1 application circuit, under 500  $\mu\text{s}$  pulse width, 10% duty cycle,  $P_{IN} = 46$  dBm.

## Features

- 2.9 - 3.5 GHz Operation
- 400 W Typical Output Power
- 10.5 dB Power Gain
- 60% Typical Drain Efficiency
- 50 Ohm Internally Matched
- <0.3 dB Pulsed Amplitude Droop

Large Signal Models Available for ADS and MWO

## Absolute Maximum Ratings (not simultaneous)

Parameter	Symbol	Rating	Units	Conditions
Pulse Width	PW	500	μs	
Duty Cycle	DC	10	%	
Drain-Source Voltage	$V_{DS}$	125	Volts	25°C
Gate-to-Source Voltage	$V_{GS}$	-10, +2	Volts	25°C
Storage Temperature	$T_{STG}$	-65, +150	°C	
Operating Junction Temperature	$T_J$	225	°C	
Maximum Forward Gate Current	$I_{GMAX}$	80	mA	25°C
Maximum Drain Current <sup>1</sup>	$I_{DMAX}$	24	A	25°C
Soldering Temperature <sup>2</sup>	$T_S$	245	°C	
Screw Torque	$\tau$	40	in-oz	
Pulsed Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.22	°C/W	100 μsec, 10%, 85°C, $P_{DISS} = 418$ W
Pulsed Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.30	°C/W	500 μsec, 10%, 85°C, $P_{DISS} = 418$ W
Case Operating Temperature	$T_C$	-40, +85	°C	

Notes:

<sup>1</sup> Current limit for long term, reliable operation

<sup>2</sup> Refer to the Application Note on soldering at <http://www.cree.com/rf/tools-and-support/document-library>

## Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
<b>DC Characteristics<sup>1</sup> (<math>T_C = 25^\circ\text{C}</math>)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-3.0	-2.3	$V_{DC}$	$V_{DS} = 10$ V, $I_D = 83.6$ mA
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-2.7	-	$V_{DC}$	$V_{DS} = 45$ V, $I_D = 0.5$ A
Saturated Drain Current <sup>2</sup>	$I_{DS}$	62.7	75.5	-	A	$V_{DS} = 6.0$ V, $V_{GS} = 2.0$ V
Drain-Source Breakdown Voltage	$V_{BR}$	150	-	-	$V_{DC}$	$V_{GS} = -8$ V, $I_D = 83.6$ mA

Notes:

<sup>1</sup> Measured on wafer prior to packaging.

<sup>2</sup> Scaled from PCM data.

## Electrical Characteristics Continued...

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
<b>RF Characteristics<sup>3</sup> (<math>T_c = 85^\circ\text{C}</math>, <math>F_o = 2.9 - 3.5\text{ GHz}</math> unless otherwise noted)</b>						
Output Power at 2.9 GHz	$P_{OUT1}$	340	375	–	W	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$
Output Power at 3.2 GHz	$P_{OUT2}$	340	400	–	W	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$
Output Power at 3.5 GHz	$P_{OUT3}$	300	360	–	W	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$
Gain at 2.9 GHz	$G_{P1}$	9.3	9.8	–	dB	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$
Gain at 3.2 GHz	$G_{P2}$	9.3	10.0	–	dB	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$
Gain at 3.5 GHz	$G_{P3}$	8.7	9.6	–	dB	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$
Drain Efficiency at 2.9 GHz	$D_{E1}$	58	66	–	%	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$
Drain Efficiency at 3.2 GHz	$D_{E2}$	53	59	–	%	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$
Drain Efficiency at 3.5 GHz	$D_{E3}$	48	57	–	%	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$
Small Signal Gain	S21	10.5	12	–	dB	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = -10\text{ dBm}$
Input Return Loss	S11	–	-8	-3.0	dB	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = -10\text{ dBm}$
Output Return Loss	S22	–	-8	-4.0	dB	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = -10\text{ dBm}$
Amplitude Droop	D	–	-0.3	–	dB	$V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$
Output Stress Match	VSWR	–	5:1	–	$\Psi$	No damage at all phase angles, $V_{DD} = 45\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{IN} = 46\text{ dBm}$ Pulsed

Notes:

<sup>3</sup> Measured in CGHV35400F-AMP1. Pulse Width = 500  $\mu\text{s}$ , Duty Cycle = 10%.

## Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Test Methodology
Human Body Model	HBM	1A (> 250 V)	JEDEC JESD22 A114-D
Charge Device Model	CDM	II (200 < 500 V)	JEDEC JESD22 C101-C

## Typical Performance

Figure 1. - CGHV35400F Typical Sparameters  
 $V_{DD} = 45\text{ V}$ ,  $I_{DQ} = 0.5\text{ A}$

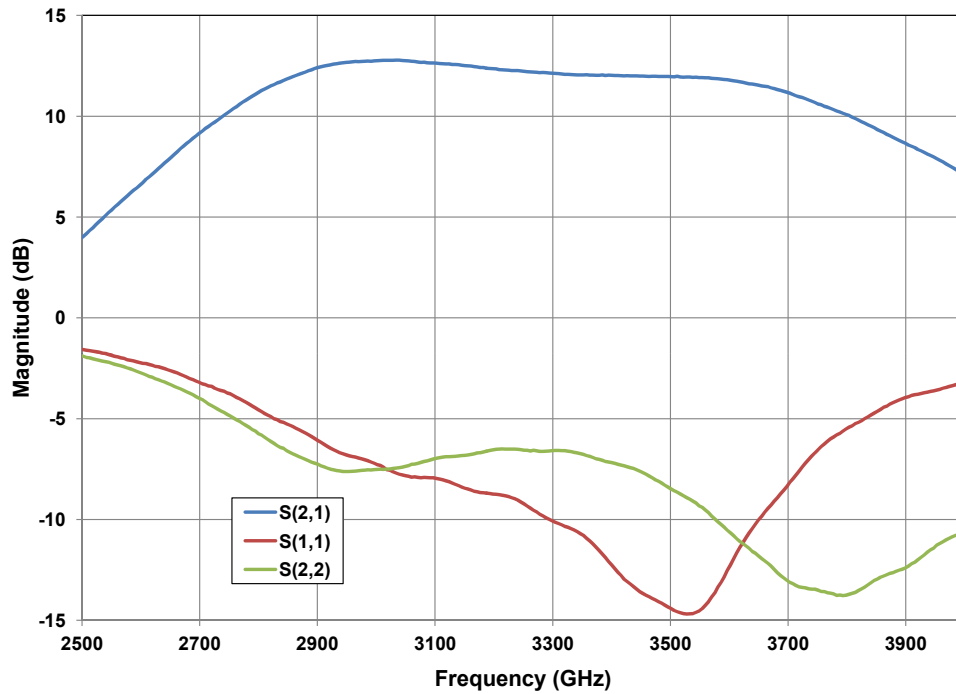
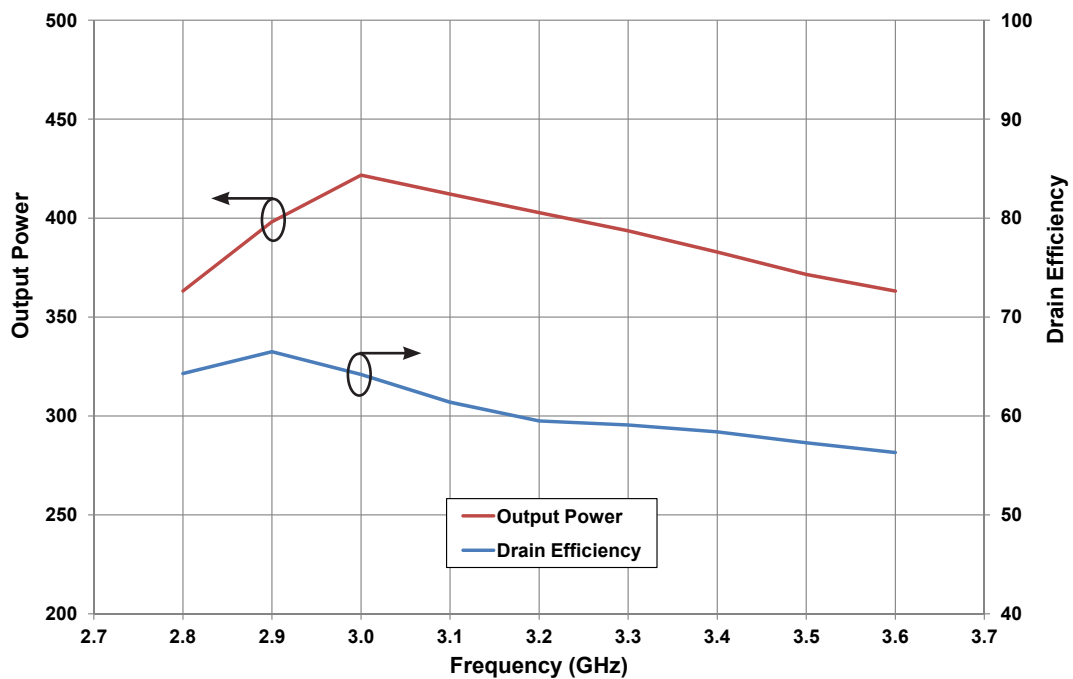
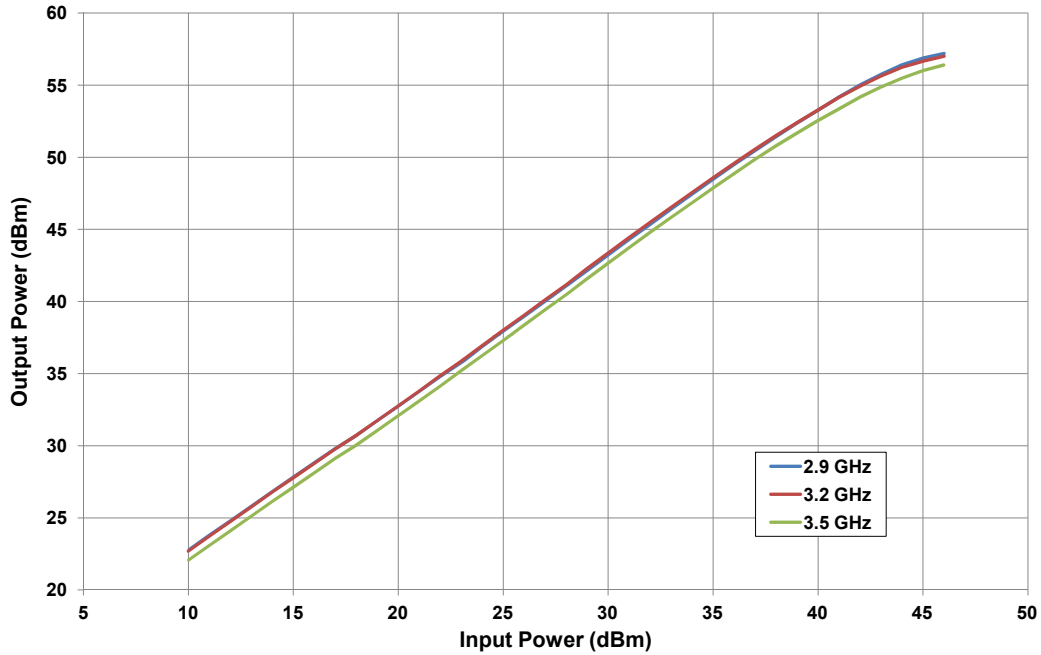


Figure 2. - CGHV35400F  $P_{OUT}$  and Drain Eff vs Frequency at  $T_{CASE} = 85^\circ\text{C}$   
 $V_{DD} = 45\text{ V}$ ,  $I_{DQ} = 0.5\text{ A}$ ,  $P_{IN} = 46\text{ dBm}$ , Pulse Width =  $500\mu\text{s}$ , Duty Cycle = 10 %

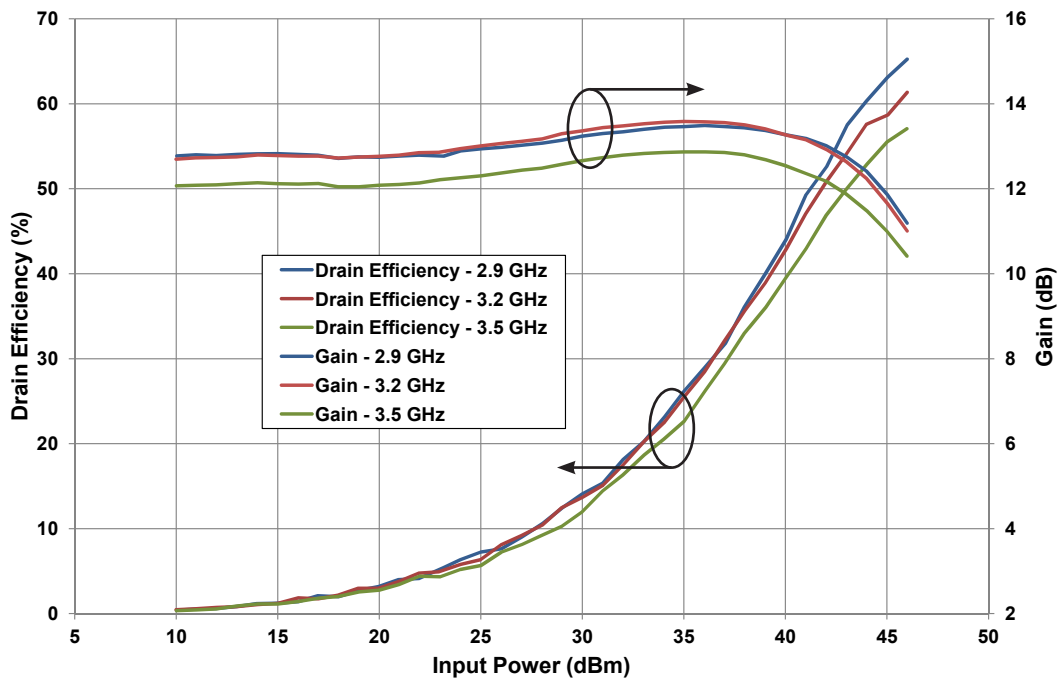


## Typical Performance

**Figure 3. - CGHV35400F Output Power vs Input Power**  
 $V_{DD} = 45\text{ V}$ ,  $I_{DQ} = 500\text{ mA}$ , Pulse Width =  $500\text{ }\mu\text{s}$ , Duty Cycle = 10 %,  $T_{case} = 85\text{ }^\circ\text{C}$



**Figure 4. - CGHV35400F Drain Efficiency & Gain vs Input Power**  
 $V_{DD} = 45\text{ V}$ ,  $I_{DQ} = 500\text{ mA}$ , Pulse Width =  $500\text{ }\mu\text{s}$ , Duty Cycle = 10 %,  $T_{case} = 85\text{ }^\circ\text{C}$

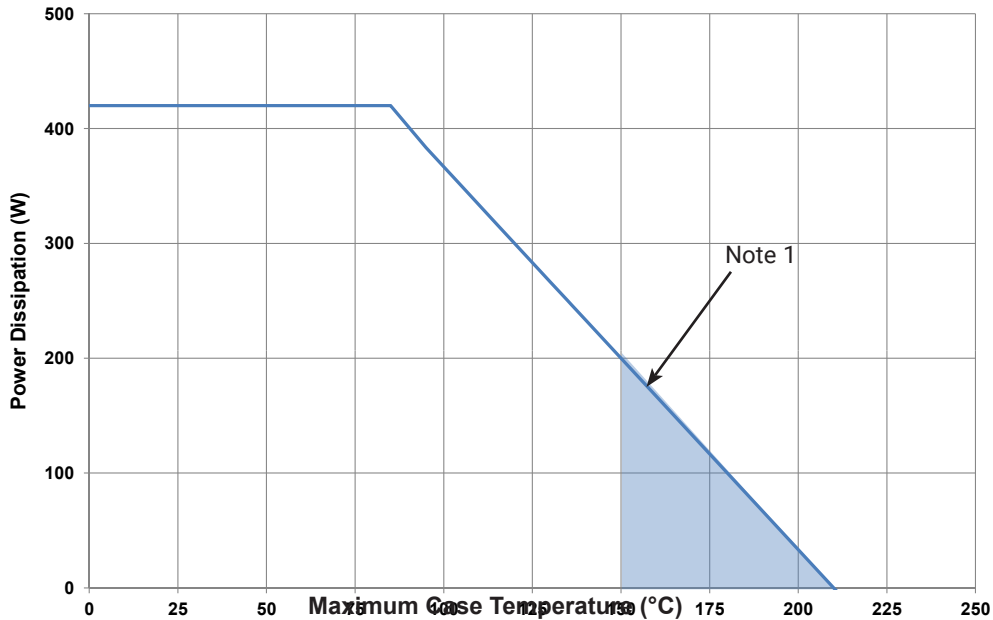


## CGHV35400F-AMP1 Application Circuit Bill of Materials

Designator	Description	Qty
R1	RES, 511, OHM, +/- 1%, 1/16W, 0603	1
R2	RES, 5.1, OHM, +/- 1%, 1/16W, 0603	1
C1	CAP, 6.8pF, +/-0.25%, 250V, 0603	1
C2, C7, C8	CAP, 10.0pF, +/-1%, 250V, 0805	3
C3	CAP, 10.0pF, +/-5%, 250V, 0603	1
C4, C9	CAP, 470pF, 5%, 100V, 0603, X	2
C5	CAP, 33000 pF, 0805, 100V, X7R	1
C6	CAP, 10uF 16V TANTALUM	1
C10	CAP, 1.0uF, 100V, 10%, X7R, 1210	1
C11	CAP, 33uF, 20%, G CASE	1
C12	CAP, 3300uF, +/-20%, 100V, ELECTROLYTIC	1
J1,J2	CONN, SMA, PANEL MOUNT JACK, FL	2
J3	HEADER, RT>PLZ, 0.1CEN LK 9POS	1
J4	CONNECTOR; SMB, Straight, JACK, SMD	1
W1	CABLE, 18 AWG, 4.2	1
-	PCB, RO4350, 2.5 X 4.0 X 0.030	1
Q1	CGHV35400F	1

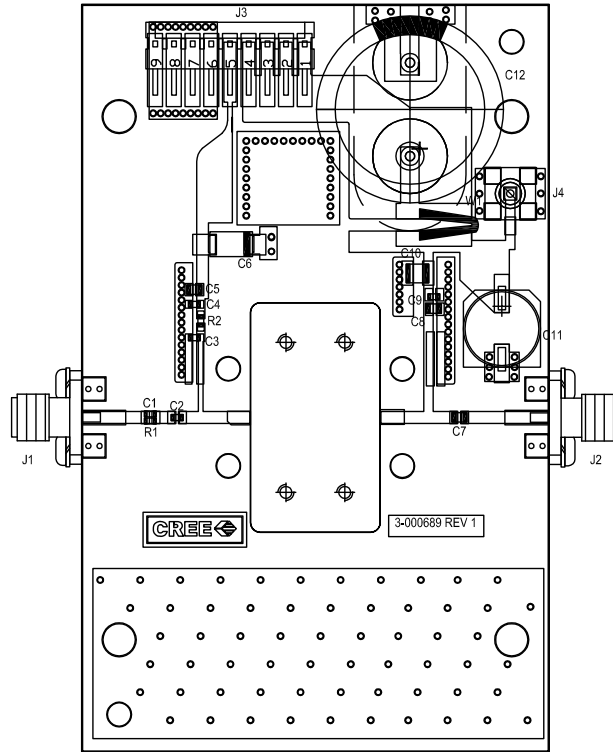
## CGHV35400F Power Dissipation De-rating Curve

Figure 5. - CGHV35400F Transient Power Dissipation De-Rating Curve

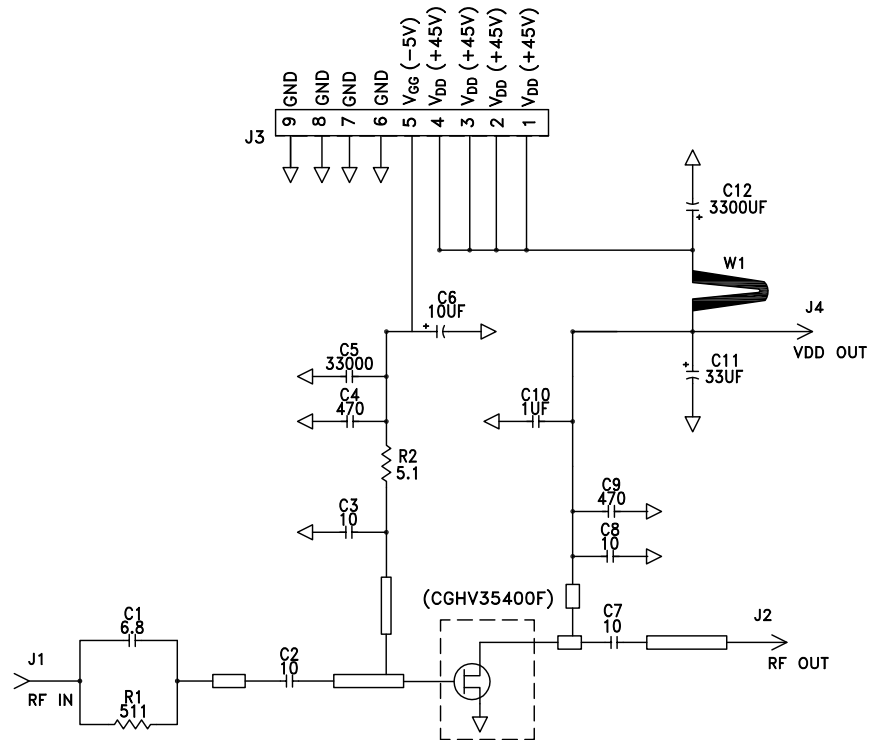


Note 1. Area exceeds Maximum Case Temperature (See Page 2).

## CGHV35400F-AMP1 Application Circuit Outline



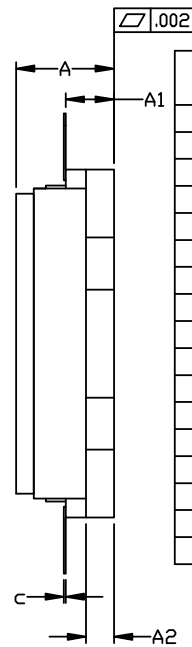
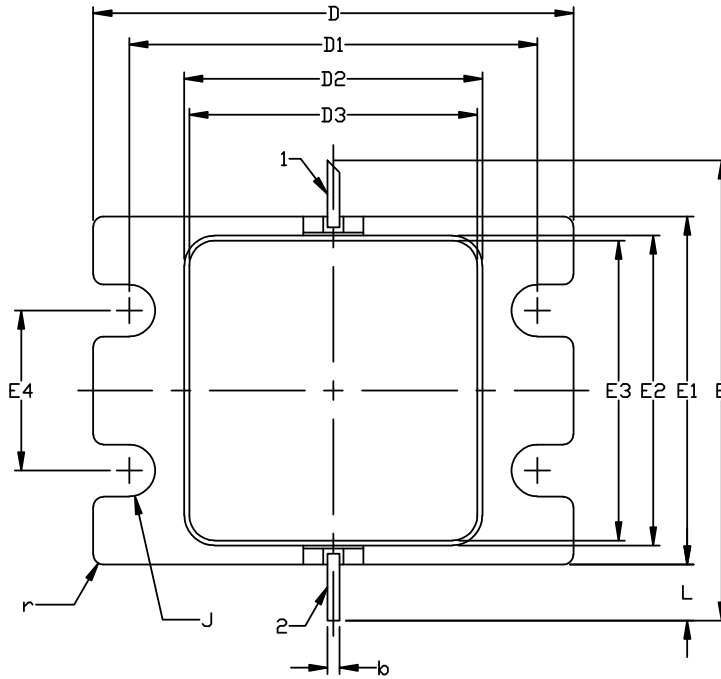
## CGHV35400F-AMP1 Application Circuit Schematic



## Product Dimensions CGHV35400F (Package Type – 440210)

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. INTERPRET DRAWING IN ACCORDANCE WITH ANSI Y14.5M-2009
2. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF .020 BEYOND EDGE OF LID
3. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF .008 IN ANY DIRECTION
4. ALL PLATED SURFACES ARE GOLD OVER NICKEL

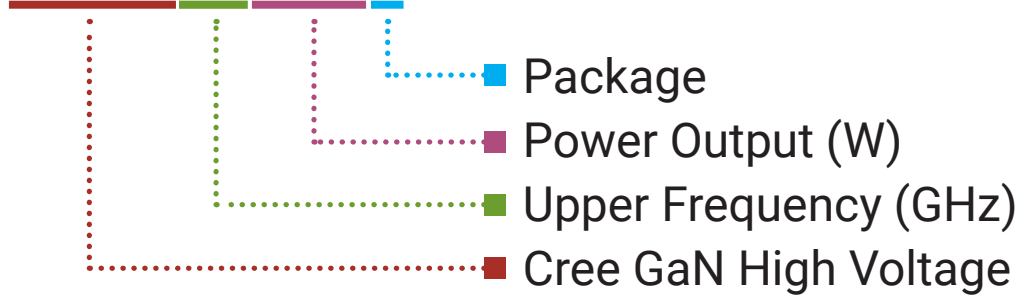


1. GATE  
2. DRAIN

DIM	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.188	0.198	4.78	5.03	
A1	0.088	0.100	2.24	2.54	2x
A2	0.049	0.061	1.24	1.55	
b	0.022	0.026	0.56	0.66	2x
c	0.002	0.006	0.05	0.15	
D	0.935	0.955	23.75	24.26	
D1	0.797	0.809	20.24	20.55	2x
D2	0.581	0.593	14.76	15.06	
D3	0.563	0.571	14.30	14.50	
E	0.906		23.01		REF
E1	0.679	0.691	17.25	17.55	
E2	0.604	0.616	15.34	15.65	
E3	0.586	0.594	14.88	15.09	
E4	0.309	0.321	7.85	8.15	2x
J	∅0.097	∅0.107	∅2.46	∅2.72	4x
L	0.090	0.130	2.29	3.30	2x
r	0.02	TYP	0.51	TYP	12x



### CGHV35400F



Parameter	Value	Units
Upper Frequency <sup>1</sup>	3.5	GHz
Power Output	400	W
Package	Flange	-

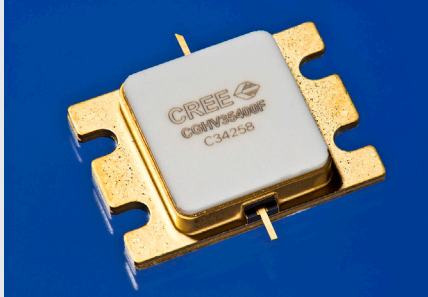
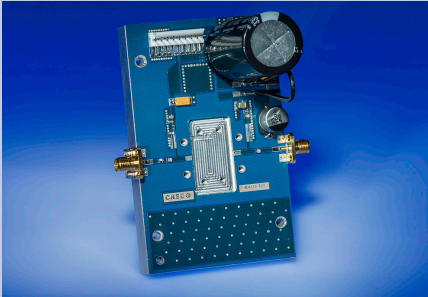
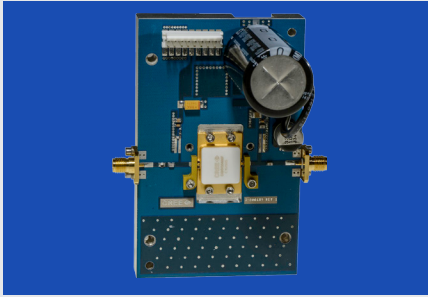
**Table 1.**

**Note<sup>1</sup>:** Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Character Code	Code Value
A	0
B	1
C	2
D	3
E	4
F	5
G	6
H	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz

**Table 2.**

## Product Ordering Information

Order Number	Description	Unit of Measure	Image
CGHV35400F	GaN HEMT	Each	
CGHV35400F-TB	Test board without GaN HEMT	Each	
CGHV35400F-AMP1	Test board with GaN HEMT installed	Each	



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